



preci-dip

## PGA / BGA / PLCC SOCKETS

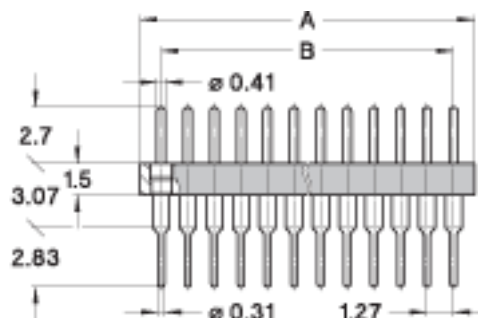
### SERIES 558

**558-10-NNNMXX-XXX101**

PGA

1.27 mm grid, Interconnect pin solder tail

Micro pin grid array sockets ( $\mu$ PGA), with contacts placed on 1.27 mm grid, interconnect pin.



### TECHNICAL SPECS.:

|                     |                          |
|---------------------|--------------------------|
| Insulator           | Glass-epoxy laminate FR4 |
| Flammability        | UL 94V-O                 |
| Pin                 | Brass CuZn36Pb3 (C36000) |
| Mechanical life     | Min. 100 cycles          |
| Rated current       | 1 A                      |
| Contact resistance  | Max. 10 m                |
| Dielectric strength | Min. 500 V RMS           |

### ORDERING INFORMATION:

| PP Plating code | Termination       | Connecting pin    |
|-----------------|-------------------|-------------------|
| 10              | Gold 0.25 $\mu$ m | Gold 0.25 $\mu$ m |

Replace NNN with the number of poles and XX-XXX with body size and layout numbers as indicated here. For example a 26x26 pin configuration with window and 478 contacts as shown here becomes 518-77-478M26-131105. Options: please consult for availability.-  $\mu$ PGA interconnect headers for SMD mount.

# TECHNICAL ASSISTANCE

## GENERAL SPECIFICATIONS:

The values listed below are general specs applying for PRECI-DIP PGA, BGA and PLCC sockets. Please see individual catalog page for additional and product specific technical data.

|                             |                                 |
|-----------------------------|---------------------------------|
| Operating temperature range | -55 ... +125 °C                 |
| Climatic category (IEC)     | 55/125/21                       |
| Operating humidity range    | annual mean 75 %                |
| Max working voltage         | 100 VRMS/150 VDC (2.54 mm grid) |

PRECI-DIP sockets are recognized by Underwriters Laboratories Inc. and listed under "Connectors for Use in Data, Signal, Control and Power Applications", File Nr. E174442

## MECHANICAL CHARACTERISTICS:

|                                   |                                                       |
|-----------------------------------|-------------------------------------------------------|
| Clip retention                    | Min. 40 N (no displacement under axial force applied) |
| Contact (sleeve / clip) retention | Min. 3.3 N acc. to MIL-DTL-83734, pt 4.6.4.2          |

## ELECTRICAL CHARACTERISTICS:

|                                                         |                            |
|---------------------------------------------------------|----------------------------|
| Insulation resistance between any two adjacent contacts | Min. 10'000 M at 500 V AC  |
| Capacitance between any two adjacent contacts           | Max. 1 pF (PLCC max. 2 pF) |
| Self inductance per contact                             | Max. 2 nH                  |

## ENVIRONMENTAL CHARACTERISTICS:

The sockets withstand the following environmental tests without mechanical and electrical defects:

- Dry heat steady state IEC 60512-11-9.11i / 60068-2-2.Bb: 125 °C, 16h
- Damp heat cyclic IEC 60512-11-12.11m / 60068-2-30.Db: 25/55 °C, 90 – 100 %rH, 1 cycle of 24 h
- Cold steady state IEC 60512-11-10.11j / 60068-2-1.A: -55 °C, 2 h
- Thermal shock IEC 60512-11-4.11d / 60068-2-14.Na: -55/125 °C, 5 cycles 30 min
- Sinusoidal vibrations IEC 60512-6-4.6d / 60068-2-6.Fc: 10 to 500 Hz, 10 g, 1 octave/min, 10 cycles for each axis
- Shock IEC 60512-6-3.6c / 60068-2-27.Ea: 50 g, 11 ms, 3 shocks in three axis

During the above two tests no contact interruption >50 ns does appear.

- Solderability J-STD-002A, Test A, 245°C, 5 s solder alloy SnAg3.8Cu0.7
- Resistance to soldering heat J-STD-0020C, 260°C, 20 s
- Moisture sensitivity J-STD-020C level 1
- Resistance to corrosion :
  - 1) Salt spray test IEC 60068-2-11.Ka: 48 h
  - 2) Sulfur dioxide (SO<sub>2</sub>) test IEC 60068-2-42 Kc: 96 h at 25 ppm SO<sub>2</sub>, 25 °C, 75 %rH
  - 3) Hydrogen sulfide (H<sub>2</sub>S) test IEC 60068-2-43 Kd: 96 h at 12 ppm H<sub>2</sub>S, 25 °C, 75 %rH

## SOLDERLESS COMPLIANT PRESS-FIT CHARACTERISTICS:

### PRESS-FIT CHARACTERISTICS MEASURED ACC. TO IEC 60352-5

- Press-in force: 90 N max. (at min. hole dia.) / 65 N typ.
- Push-out force: 30 N min. (at max. hole dia.) / 50 N typ.
- Push-out 3rd cycle: 20 N min. (at max. hole dia.)

### PCB HOLE DIMENSIONS

- 2.54 mm grid: Finished hole Ø: 1 + 0.09/-0.06 mm | Drilled hole Ø: 1.15 ± 0.02 mm

- Interstitial grid: Finished hole Ø:  $0.7 + 0.09/-0.06$  mm | Drilled hole Ø:  $0.8 \pm 0.02$  mm

#### **PCB HOLE PLATING**

- PCB surface finish: Hole plating
- Tin: 5-15 µm tin over min. 25 µm copper
- Copper: min. 25 µm copper
- Gold over nickel: 0.05-0.2 µm gold over 2.5-5 µm nickel over min. 25 µm copper